

# Solder Joint Reliability of BGA CSP Flip Chip and Fine Pitch SMT Assemblies

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## BOOK DETAILS

- Author : John H. Lau
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## **BOOK SYNOPSIS**

This new volume by interconnection expert on solder joints, Johns H. Lau, deals with BGA, CSP, Flip Chips, and other new technologies that underlie the electronics industry's need for smaller, faster products. Naturally, as ever-smaller products are created, the reliability of the solder joints that bind them becomes increasingly crucial. Balancing concepts and practical applications, the authors explain the fundamentals of solder joint reliability and present creative, robust packaging techniques for cost-effective interconnection.

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